

Claims:

1. An optoelectronic device (30,50,60,70,80,90), comprising an open-ended metal canister (36,56,66,76,86), an insulating
5 substrate (34,54,64,74,84,94), at least one optoelectronic component (42,82,92) mounted on said substrate, and one or more electrical connections (39,44,49,79,89,109) made to said component(s) (42,82,92), wherein:
 - the insulating substrate (34,54,64,74,84,94) closes the
10 open end (37) of the metal canister (36,56,66,76,86) so that the metal canister and insulating substrate (34,54,64,74,84,94) together form a housing (32,52,62,72,82,92) for one or more of said components mounted on the substrate;
 - the insulating substrate (34,54,64,74,84,94) acts as a
15 circuit board to carry said electrical connections from said component(s) externally of the housing (32,52,62,72,82,92); and
 - the canister (36,56,66,76,86) has at least one optical port (38,58,68,78,88,98) by which optical radiation
20 (45,55,65,75,85) may be transmitted into and/or out of said housing (32,52,62,72,82,92).
2. An optoelectronic device (30,50,60,70,80,90) as claimed in Claim 1, in which the housing (32,52,62,72,82,92) is
25 hermetically sealed.
3. An optoelectronic device (30,50,70,80) as claimed in Claim 1 or Claim 2, in an optical port includes an optical window (38,58,78,88).
- 30 4. An optoelectronic device (60) as claimed in Claim 1 or

Claim 2, in which an optical port includes a receptacle (68) for an optical component (61).

5 5. An optoelectronic device (30) as claimed in any preceding claim, in which at least one electrical connection includes at least one via (49,109) through said insulating substrate (34).

10 6. An optoelectronic device (90) as claimed in Claim 5, in which said via (109) extends to a side (97) of the substrate (94) opposite from a side (93) of the substrate (94) that closes the open end (107) of the canister (96).

15 7. An optoelectronic device (30) as claimed in Claim 6, in which at least one electrical connection includes a track (44) on or within said substrate (34) that extends towards an edge (47) of said substrate.

20 8. An optoelectronic device (30) as claimed in any preceding claim, in which the substrate (34) includes a multilayer printed circuit board (36) for making electrical connections internally and/or externally of said housing (32).

25 9. An optoelectronic device (30) as claimed in any preceding claim in which the substrate (36) includes a printed metallic layer (35) to which the open end (37) of the canister (36) is bonded.

30 10. An optoelectronic device (30,50,60,70,90) as claimed in any preceding claim, in which the substrate is a ceramic

substrate (34,54,64,74,94).

11. An optoelectronic device (80) as claimed in any of
Claims 1 to 9, in which the substrate is a flex substrate
5 (84).